

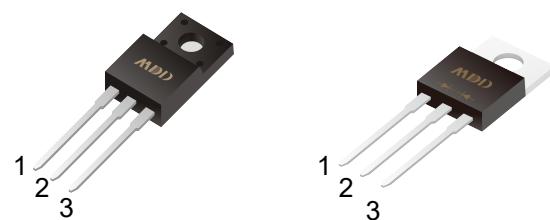
**MDD12N65F/MDD12N65P**

650V N-Channel Enhancement Mode MOSFET

V_{DS}	650 V
I_{D(TC=25°C)}	12A
R_{DS(on),max}	0.8Ω@V_{GS}=10V
Q_{g,typ}	41.9nC

TO-220F-3L

TO-220-3L



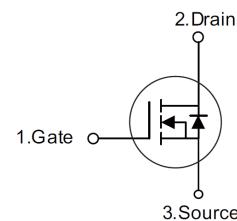
General Features

- Ultra low gate charge
- Low reverse transfer Capacitance
- Fast switching capability
- Avalanche energy tested
- Improved dv/dt capability, high ruggedness

Application

- High efficiency switch mode power supplies
- Electronic lamp ballasts based on half bridge
- LED power supplies

Equivalent Circuit



Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	650	V
Gate-Source Voltage	V _{GS}	±30	V
Continuous Drain Current	I _D	12	A
Pulsed Drain Current(Note 1)	I _{DM}	48	A
Avalanche Energy Single Pulsed (Note 2)	E _{AS}	500	mJ
Continuous diode forward current	I _S	12	A
Diode pulse current	I _{S,pulse}	48	A
Peak Diode Recovery dv/dt (Note 3)	dv/dt	5	V/ns
Power Dissipation TO-220F	P _D	42	W
Power Dissipation TO-220		150	W
Junction Temperature	T _J	150	°C
Storage Temperature	T _{stg}	-55 ~ 150	°C

Thermal Characteristics

Parameter	Symbol	Value		Unit
		TO-220F	TO-220	
Thermal resistance, Junction-to-case	R _{θJC}	2.98	0.83	°C/W
Thermal resistance, Junction-to-ambient	R _{θJA}	110	62.5	°C/W

- Notes:**
1. Pulse width limited by maximum junction temperature.
 2. L=10mH, IAS = 10A, Starting T_j= 25°C.
 3. ISD = 12A, di/dt≤100A/us, VDD≤BVDS, Starting T_j= 25°C.



T_a = 25°C unless otherwise specified

Symbol	Parameter		Condition	Min	Typ	Max	Unit
V _{(BR)DSS}	Drain-Source Breakdown Voltage		V _{GS} =0V, I _D =250μA	650	--	--	V
I _{GSS}	Gate-Source Leakage Current	Forward	V _{GS} =30V, V _{DS} =0V	--	--	100	nA
		Reverse	V _{GS} =-30V, V _{DS} =0V	--	--	-100	nA
I _{bss}	Drain-Source Leakage Current		V _{DS} =650V, V _{GS} =0V	--	--	1	uA
V _{GS(TH)}	Gate Threshold Voltage		V _{DS} =V _{GS} , I _D =250μA	2.0	--	4.0	V
R _{DSS(ON)}	Drain-Source On-State Resistance		V _{GS} =10V, I _D =6A	--	0.64	0.8	Ω

Dynamic Electrical Characteristics

Symbol	Parameter	Condition	Min	Typ	Max	Unit
C _{iss}	Input Capacitance	V _{DS} =25V V _{GS} =0V f=1MHz	--	2000	--	pF
C _{oss}	Output Capacitance		--	164	--	pF
C _{rss}	Reverse Transfer Capacitance		--	7.4	--	pF
Q _g	Total Gate Charge	V _{DS} =520V, V _{GS} =10V, I _D =12A (Note1,2)	--	41.9	--	nC
Q _{gs}	Gate Source Charge		--	10.8	--	nC
Q _{gd}	Gate Drain Charge		--	15	--	nC

Switching Characteristics

Symbol	Parameter	Condition	Min	Typ	Max	Unit
t _{d(on)}	Turn on Delay Time	V _{DS} =325V, I _D =12A, R _G =10Ω (Note1,2)	--	--	14.6	ns
t _r	Turn on Rise Time		--	--	37.8	ns
t _{d(off)}	Turn Off Delay Time		--	--	69.3	ns
t _f	Turn Off Fall Time		--	--	15.8	ns

Source Drain Diode Characteristics

Symbol	Parameter	Condition	Min	Typ	Max	Unit
I _{SD}	Source drain current(Body Diode)		--	--	12	A
I _{SM}	Pulsed Current		--	--	48	A
V _{SD}	Drain-Source Diode Forward Voltage	I _S =12A, V _{GS} =0V	--	--	1.5	V
t _{rr}	Body Diode Reverse Recovery Time	V _R =325 I _F =12A, -dI/F/dt =100A/μs	--	450.4	--	ns
Q _{rr}	Body Diode Reverse Recovery Charge		--	4.75	--	uC

Notes:

1.Pulse test ; Pulse width≤300us, duty cycle≤2%.

2.Essentially independent of operating temperature.

Electrical Characteristics Diagrams

Figure 1. Typical Output Characteristics

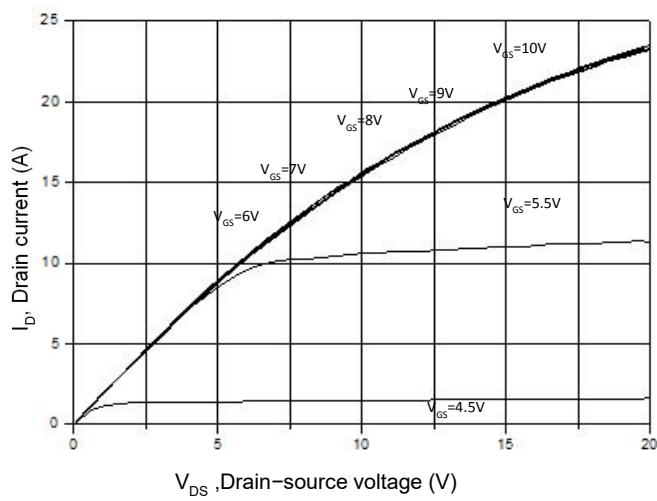


Figure 3. On-Resistance Variation vs. Drain Current

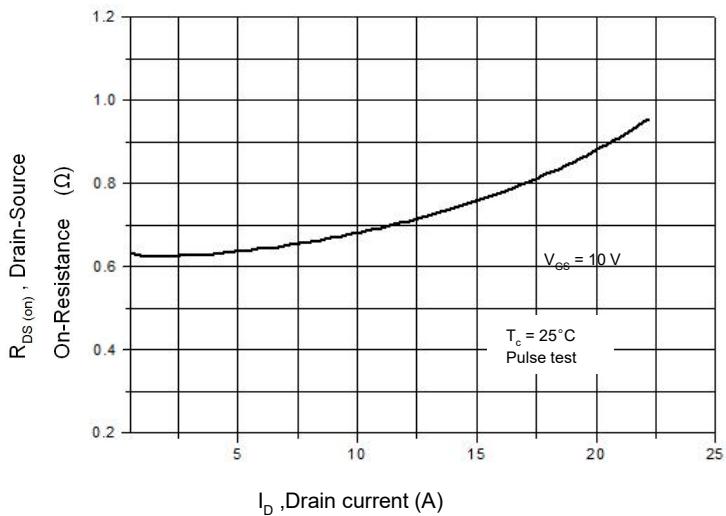


Figure 5. Breakdown Voltage vs. Temperature

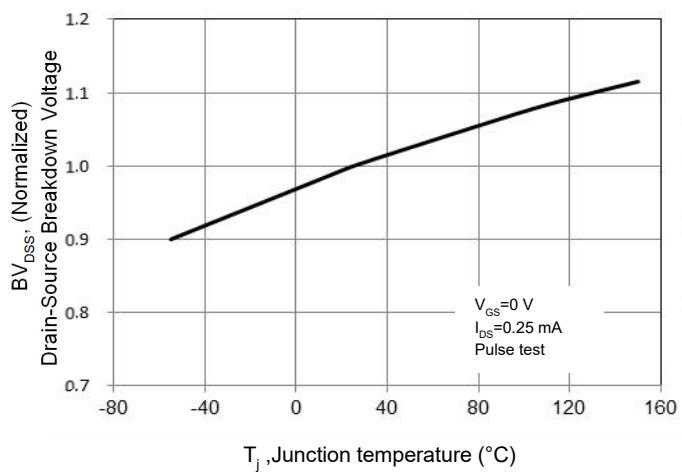


Figure 2. Transfer Characteristics

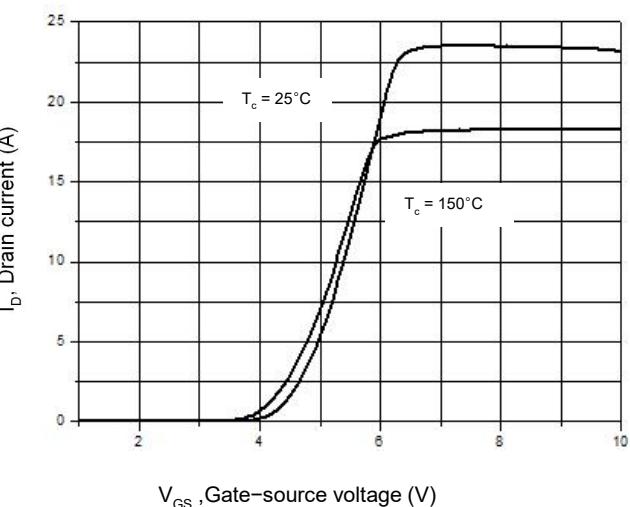


Figure 4. Threshold Voltage vs. Temperature

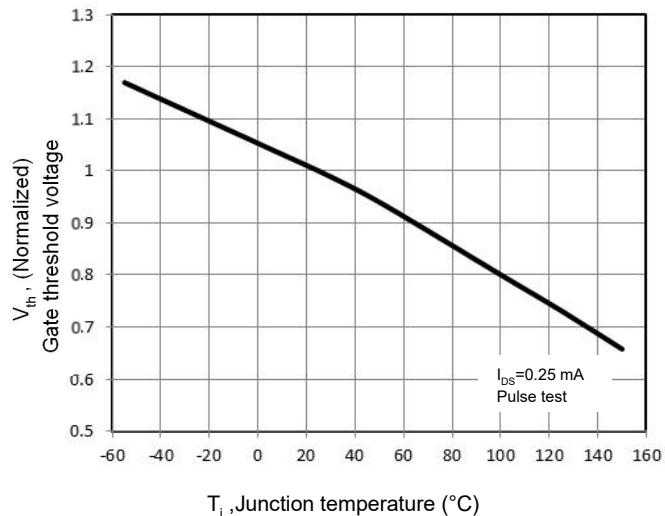


Figure 6. On-Resistance vs. Temperature

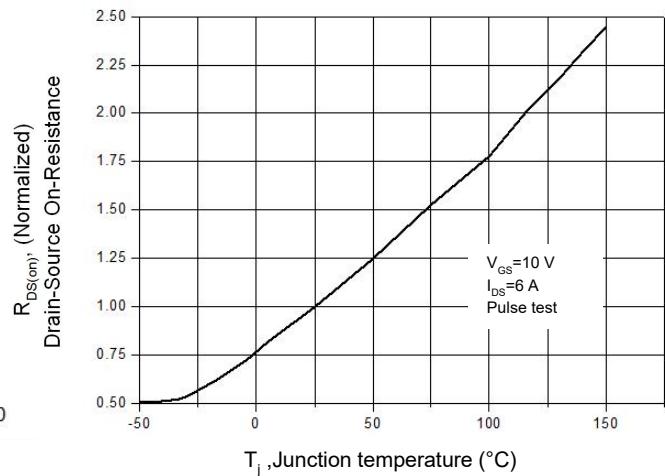


Figure 7. Capacitance Characteristics

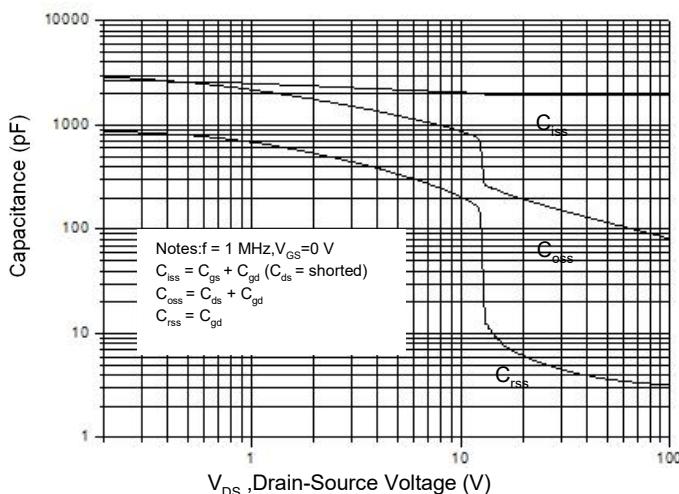


Figure 9. Maximum Safe Operating Area

TO-220F

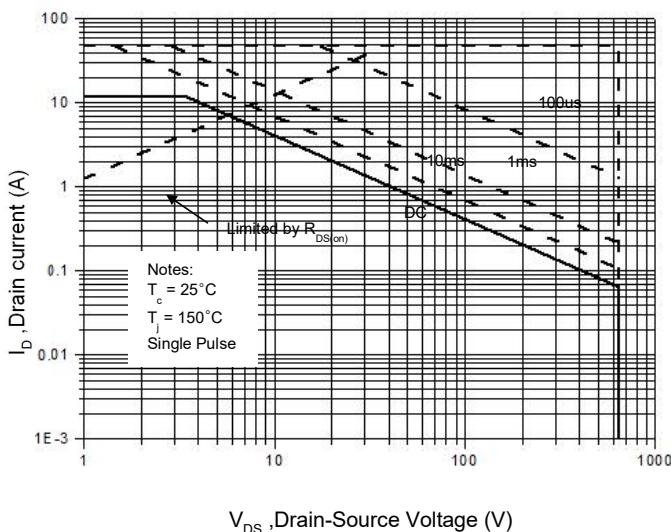


Figure 11. Power Dissipation vs. Temperature

TO-220F

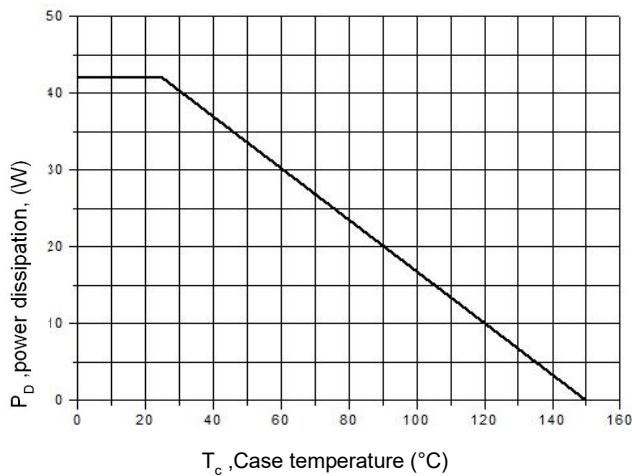


Figure 8. Gate Charge Characteristics

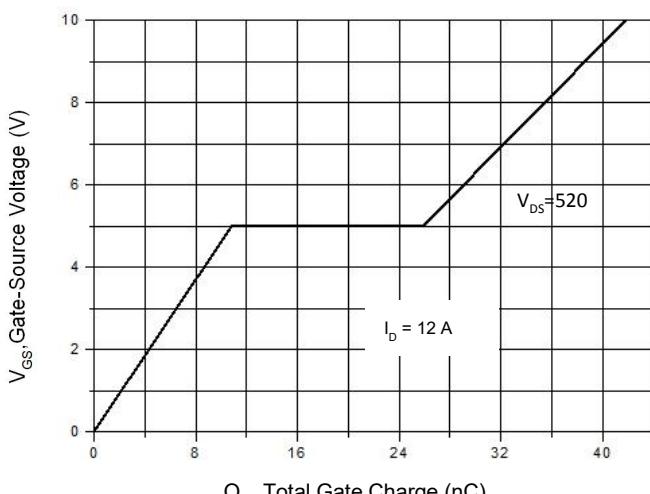


Figure 10. Maximum Safe Operating Area

TO-220

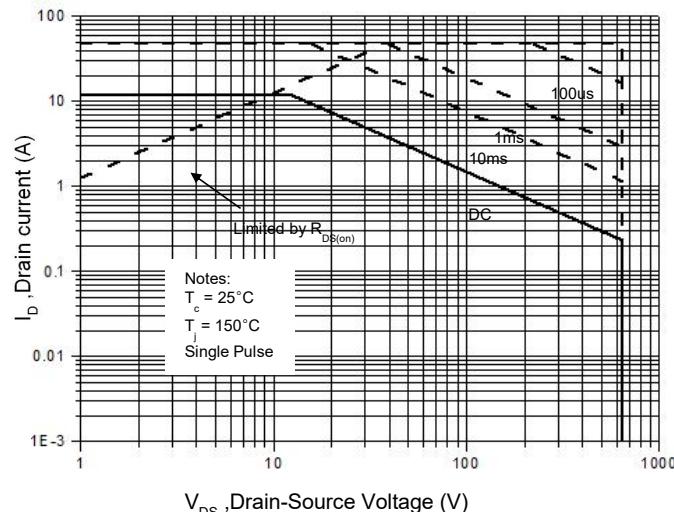


Figure 12. Power Dissipation vs. Temperature

TO-220

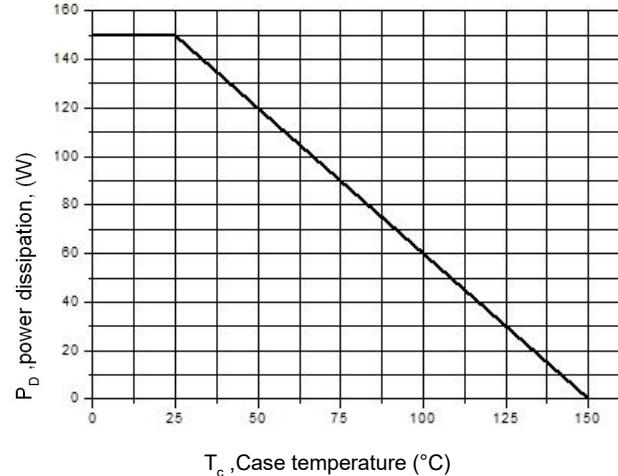


Figure 13. Continuous Drain Current vs. Temperature

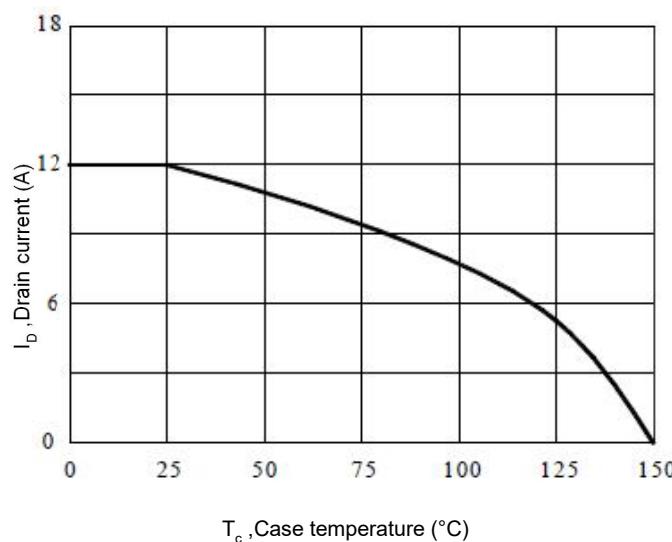


Figure 14. Body Diode Transfer Characteristics

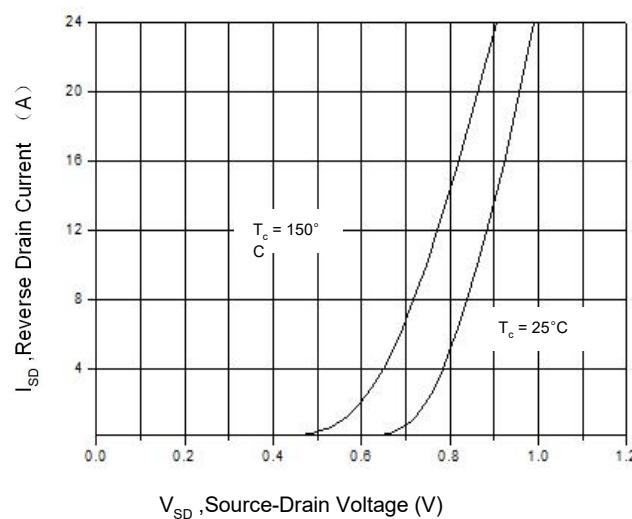


Figure 15 Transient Thermal Impedance, Junction to Case, TO-220F

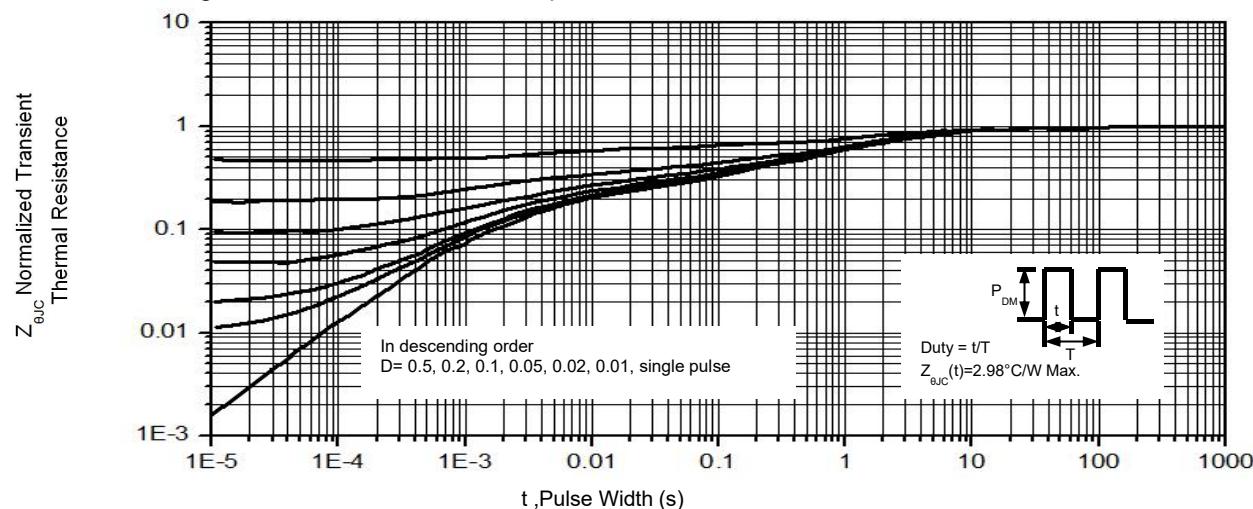
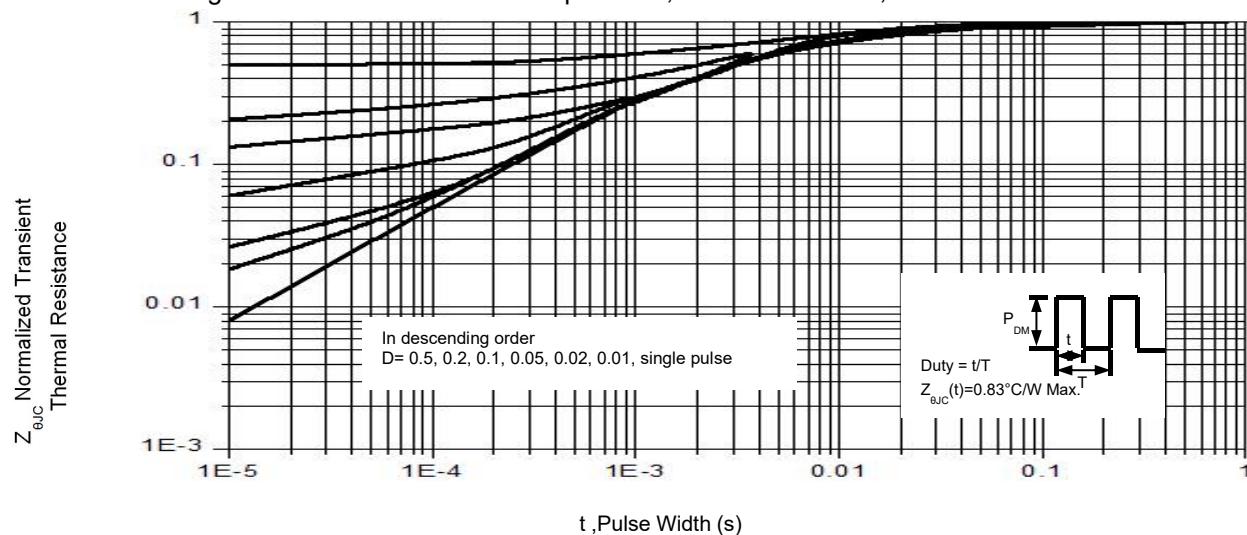
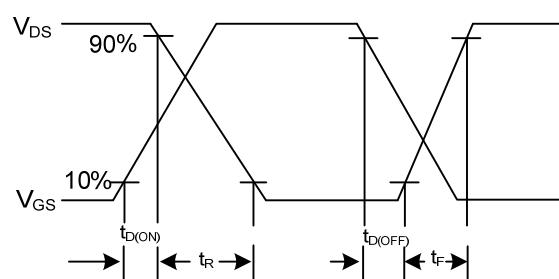
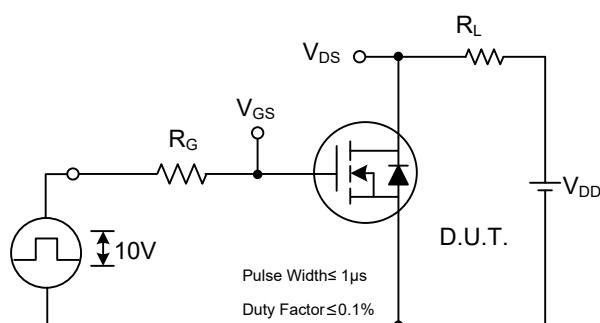
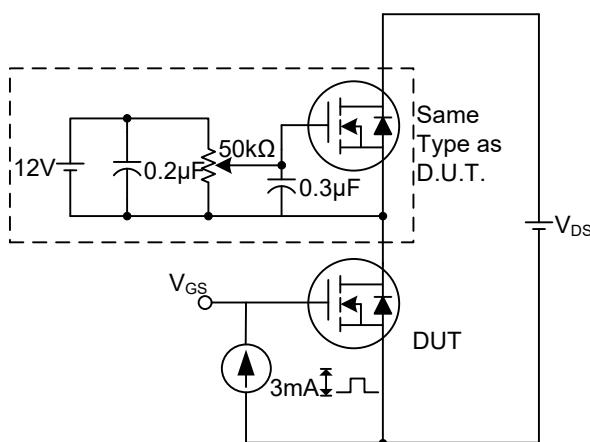
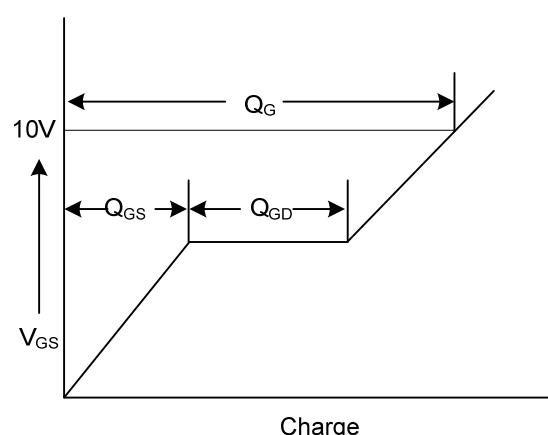
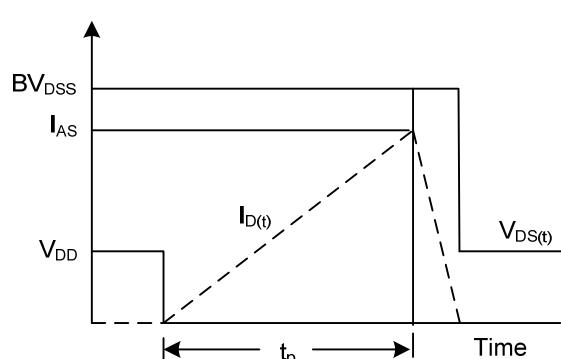
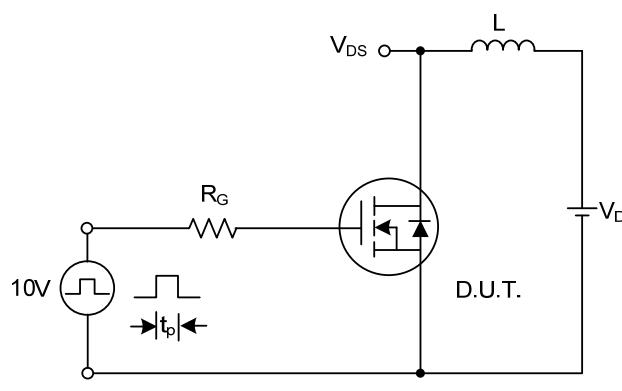


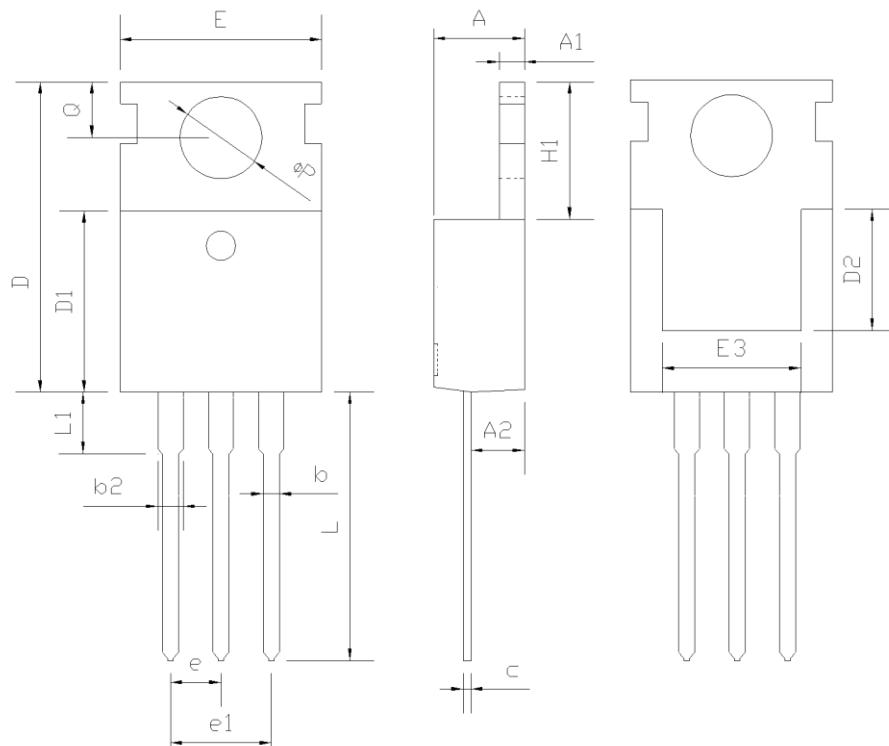
Figure 16. Transient Thermal Impedance, Junction to Case, TO-220



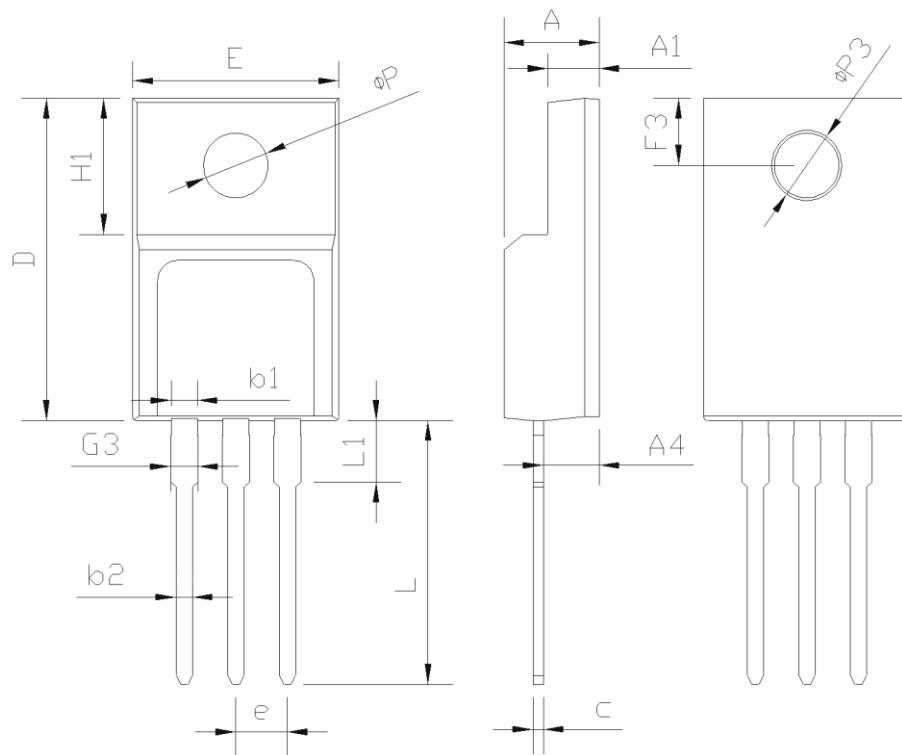

Switching Test Circuit

Switching Waveforms

Gate Charge Test Circuit
Gate Charge Waveform

Unclamped Inductive Switching Test Circuit
Unclamped Inductive Switching Waveforms

The curve above is for reference only.

Mechanical Dimensions for TO-220-3L



SYMBOL	mm		
	MIN	NOM	MAX
A	4.37	4.57	4.70
A1	1.25	1.30	1.40
A2	2.20	2.40	2.60
b	0.70	0.80	0.95
b2	1.17	1.27	1.47
c	0.45	0.50	0.60
D	15.10	15.60	16.10
D1	8.80	9.10	9.40
D2	5.50	-	-
E	9.70	10.00	10.30
E3	7.00	-	-
e	2.54 BSC		
e1	5.08 BSC		
H1	6.25	6.50	6.85
L	12.75	13.50	13.80
L1	-	3.10	3.40
ΦP	3.40	3.60	3.80
Q	2.60	2.80	3.00

Mechanical Dimensions for TO-220F-3L


SYMBOL	mm		
	MIN	NOM	MAX
E	9.96	10.16	10.36
A	4.50	4.70	4.90
A1	2.34	2.54	2.74
A4	2.56	2.76	2.96
c	0.40	0.50	0.65
D	15.57	15.87	16.17
H1	6.70REF		
e	2.54BSC		
L	12.68	12.98	13.28
L1	2.88	3.03	3.18
ΦP	3.03	3.18	3.38
ΦP3	3.15	3.45	3.65
F3	3.15	3.30	3.45
G3	1.25	1.35	1.55
b1	1.18	1.28	1.43
b2	0.70	0.80	0.95

Package Marking and Ordering Information

Part Number	Marking	Package	Units/Tube	Units/Reel
MDD12N65F	12N65F	TO-220F	50	
MDD12N65P	12N65P	TO-220-3L	50	